



**BRIGHTTEK**  
**BRIGHTTEK (EUROPE) LIMITED**

*Brighten up The World With LED!*



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

## PRODUCT DATASHEET



- ▶ PCB / CHIP LED
- ▶ 0603 (1608) 0.4t
- ▶ Green 570nm

**NOG01S77**



Release Date: 13 December 2022 Version: A1.2



### 0603 (1608) 0.4t

**RoHS**  
Compliant



#### FEATURES:

- **Package:** PCB / CHIP LED Top View
- **Forward Current:** 20mA
- **Forward Voltage (typ.):** 2.1V
- **Luminous Intensity (typ.):** 50mcd@20mA
- **Colour:** Green
- **Wavelength (typ.):** 565-576nm
- **Viewing angle:** 140°
- **Materials:**
  - Lead Frame: PCB
  - Resin: Epoxy (Water Clear)
  - Finish: Au Plated
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+100°C
- **ESD (HBM):** 2kV
- **Grouping parameters:**
  - Forward voltage
  - Luminous intensity
  - Dominant wavelength
- **Soldering methods:** Reflow
- **MSL:** acc. to JEDEC Level 2a
- **Packing:** 8mm tape with max.4000/reel,  $\phi$ 180mm (7")

#### APPLICATIONS:

- Backlighting
- Indication Light
- Switch light
- Dashboard
- Consumer Goods
- 3C Products

## CHARACTERISTICS:

### Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I <sub>F</sub>	30	mA
Peak Forward Current Duty 1/10; width 0.1ms	I <sub>FP</sub>	100	mA
Power Dissipation	P <sub>D</sub>	80	mW
Reverse Voltage	V <sub>R</sub>	8	V
Reverse Current @8V	I <sub>R</sub>	10	μA
Junction Temperature	T <sub>j</sub>	110	°C
Operating Temperature	T <sub>OPR</sub>	-40~+85	°C
Storage Temperature	T <sub>STG</sub>	-40~+100	°C

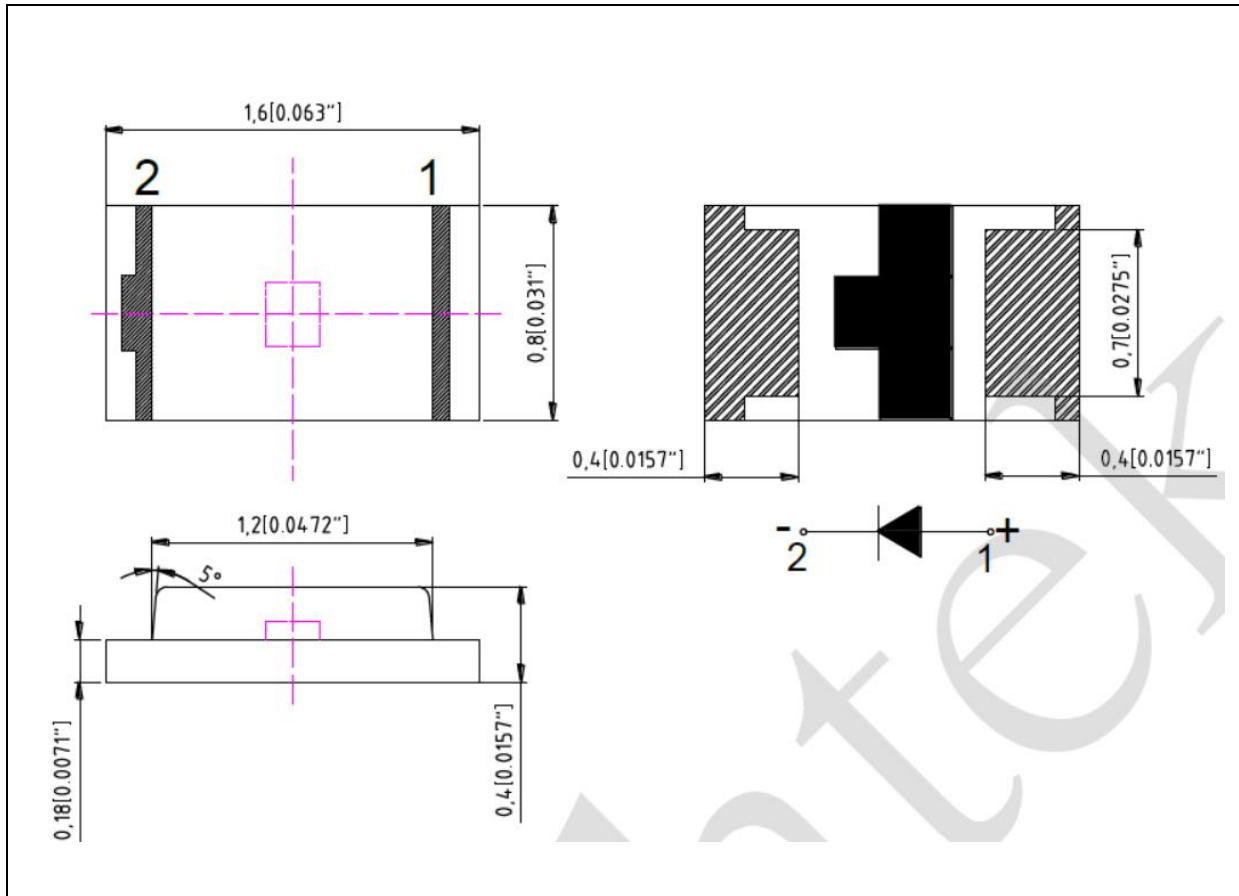
### Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V <sub>F</sub>	1.6	---	2.5	V	I <sub>F</sub> =20mA
Luminous Intensity	I <sub>v</sub>	30	50	---	mcd	I <sub>F</sub> =20mA
Dominant Wavelength	λ <sub>D</sub>	565	---	576	nm	I <sub>F</sub> =20mA
Viewing Angle	2θ <sub>1/2</sub>	---	140	---	deg	I <sub>F</sub> =20mA

- Luminous intensity (I<sub>v</sub>) ±10%, Forward Voltage (V<sub>F</sub>) ±0.1V.

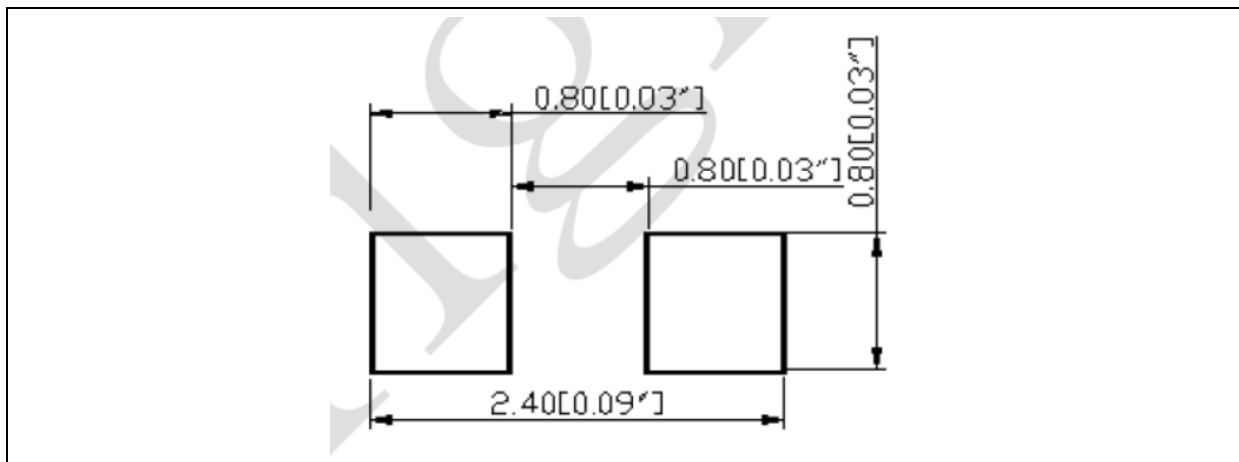
## OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance  $\pm 0.2$ mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance  $\pm 0.1$ mm with angle tolerance  $\pm 0.5^\circ$ .

**BINNING GROUPS:**


---

 Forward Voltage Classifications ( $I_F = 20\text{mA}$ ):

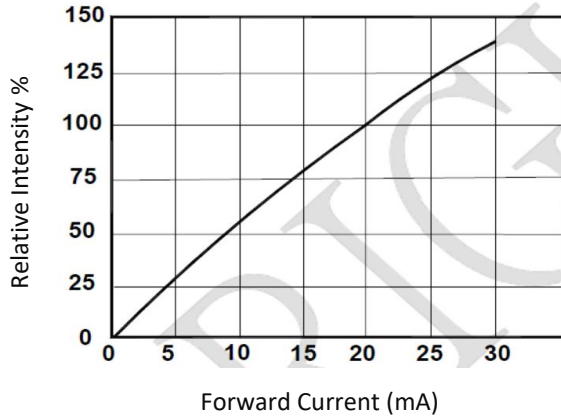
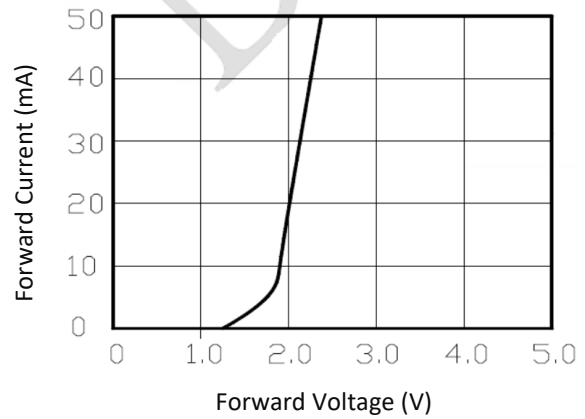
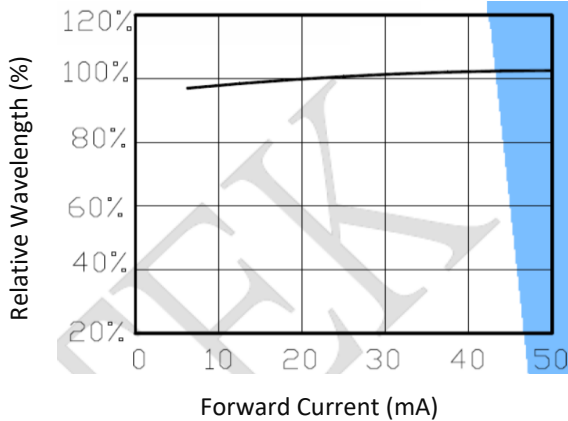
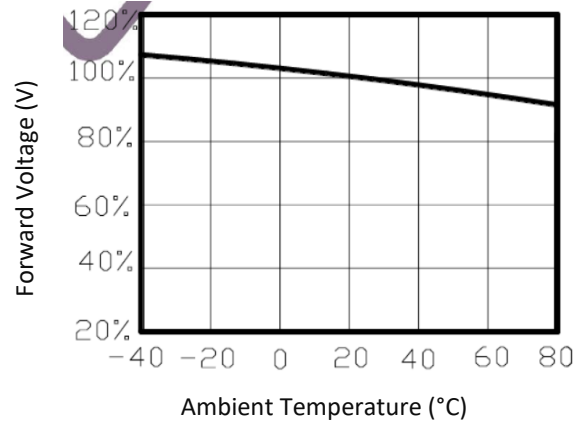
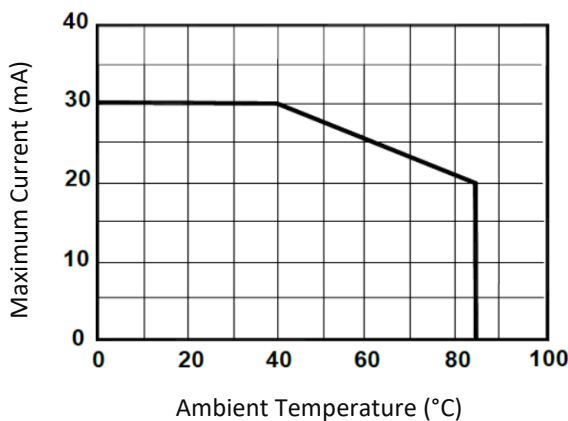
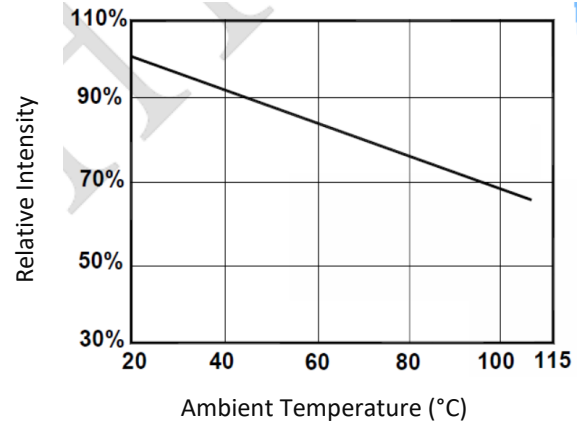
Code	Min.	Max.	Unit
b	1.6	1.9	V
c	1.9	2.2	
d	2.2	2.5	

 Luminous Intensity Classifications ( $I_F = 20\text{mA}$ ):

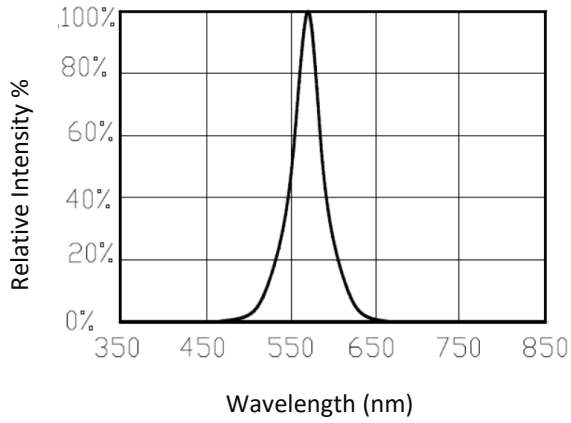
Code	Min.	Max.	Unit
E	30	40	mcd
F	40	50	
G	50	63	
H	63	80	
I	80	100	

 Dominant Wavelength Classifications ( $I_F = 20\text{mA}$ ):

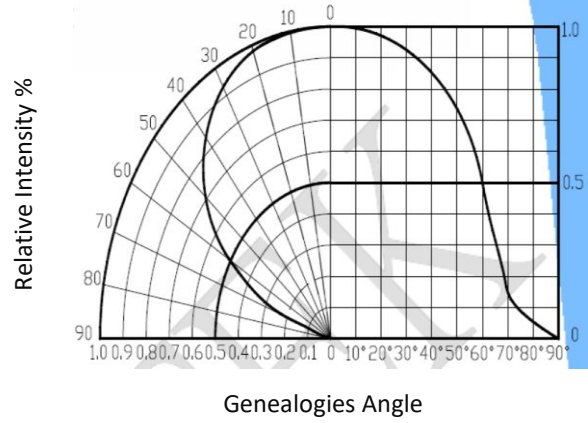
Code	Min.	Max.	Unit
h	565	568	nm
i	568	572	
j	572	576	

**ELECTRO-OPTICAL CHARACTERISTICS:**
**Relative Intensity v.s. Forward Current**

**Forward Current v.s. Forward Voltage**

**Forward Current v.s. Wavelength**

**Forward Voltage v.s. Temperature**

**Temperature Derating Chart**

**Relative Intensity Flux v.s. Junction Temperature**


Relative Intensity v.s. Wavelength

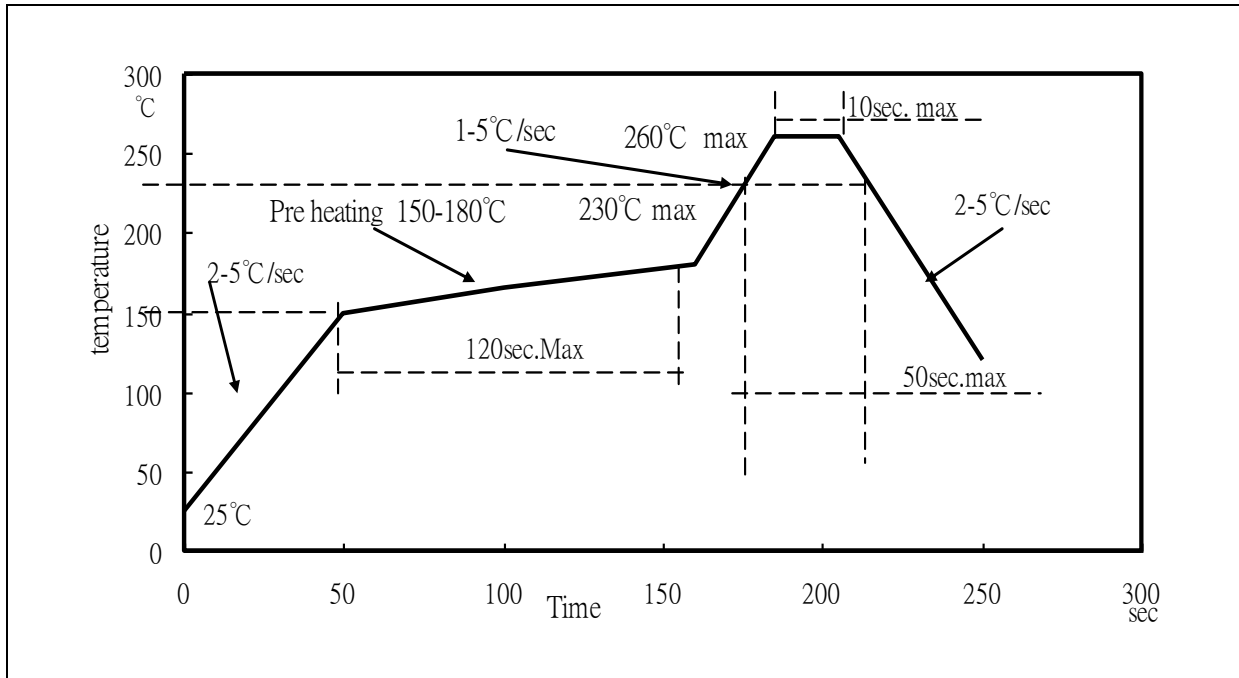


Relative Intensity v.s. Angular Displacement



## RECOMMENDED SOLDERING PROFILE:

Lead Free IR reflow solder:

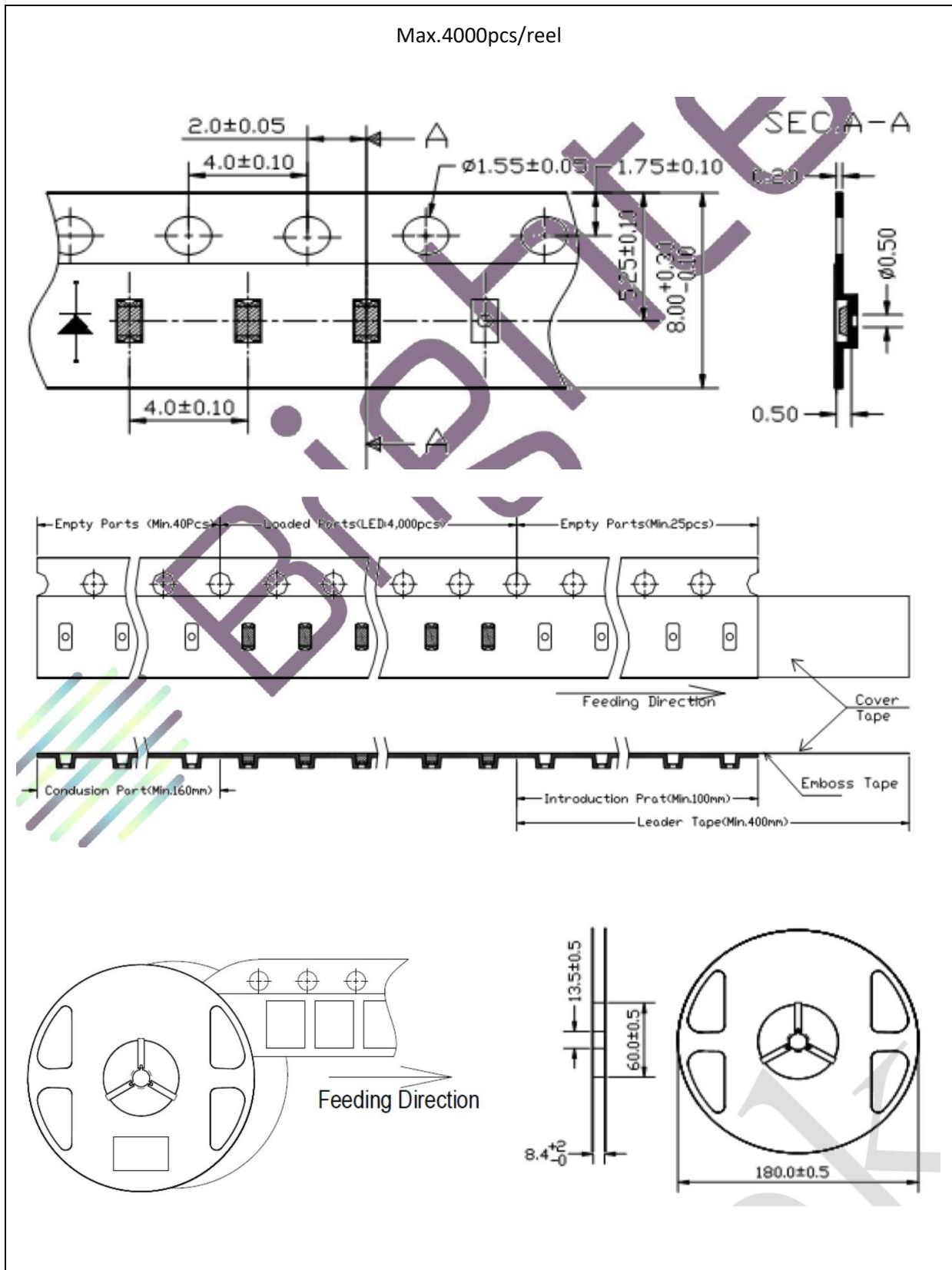


Note:

1. Recommend reflow temperature 240°C. The maximum soldering temperature should be limited to 260°C.
2. Maxima reflow soldering: 3 times.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.

**PACKING SPECIFICATION:**

Reel Dimension:





## PRECAUTIONS OF USE:

---

### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking before use.

### Baking:

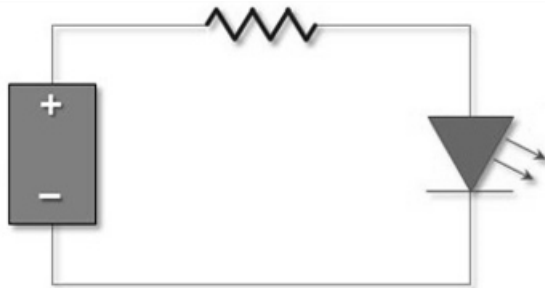
It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs.

The suggested baking conditions are as followings:

- 60±3°C x 6hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

### Testing Circuit:



Must apply resistor(s) for protection (over current proof).

### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

**REVISION RECORD:**

---

Version	Date	Summary of Revision
A1.0	09/05/2017	Datasheet set-up.
A1.1	23/05/2022	New datasheet format.
A1.2	13/12/2022	Revised ESD and MSL level.